

RECEIVED
CENTRAL FAX CENTER

APR 17 2007

Remarks

Claims 1-23 are pending in this application. Claims 1 and 12 were amended to specify that the surface is passivated by contacting it with a metallocene and no other reactants. Support for this amendment may be found throughout the specification, including at paragraphs [0012] and [0017].

Summary of Interview

Applicants' representative thanks Examiners Stark and Toledo for the courtesy of the telephonic interview of April 17, 2007. During the interview, the pending claims, prior art references and possible amendments were discussed. Applicants appreciate the Examiners' suggestions as to amendments and have amended the claims accordingly. It was agreed that the amendments would overcome the pending rejections. Examiner Toledo requested that that Applicants point to paragraph [0017] as support for the current amendment.

Rejections Under 35 §§ USC 102 and 103

All claims have been rejected as being anticipated by U.S. Patent No. 4,927,670 ("Erbil") and as being obvious over Lopatin et al. US Patent Application No. 2005/0085031 ("Lopatin") in view of Erbil.

As discussed in the April 17, 2007 interview, both Erbil and Lopatin discuss using metallocenes as precursors to deposit a metal layer on a surface.

The present claims involve exposing an exposed copper surface to a metallocene compound to passivate the surface. Unlike Erbil and Lopatin, in the embodiments described by the present claims, the metallocene is not used as a precursor to deposit a metal layer. This is made clear at least by the recitation in the present claims that the surface is passivated "by contacting the exposed copper surface with a metallocene compound and no other reactants." At least because this feature is neither taught nor suggested by the references, either alone or in combination, Applicants submit that the pending claims are patentable and request a Notice of Allowance.


APR 17 2007

CONCLUSION

Should the Examiner believe that a telephone conference would expedite the prosecution of this application, the undersigned can be reached at the telephone number set out below.

Dated: April 17, 2007

Respectfully submitted,
BEYER WEAVER, LLP


Denise Bergin
Registration No. 50,581

P.O. Box 70250
Oakland, CA 94612-0250
(510) 663-1100